503191174 02/24/2015

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3237792

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ching-Wen Hung	02/09/2015
Jia-Rong Wu	02/09/2015
Chih-Sen Huang	02/09/2015
Yi-Wei Chen	02/09/2015
Chia Chang Hsu	02/09/2015

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.	
Street Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park		
City: Hsin-Chu City		
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14629502

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU Address Line 1: P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP2420USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	02/24/2015

Total Attachments: 10 source=2184915#page1.tif source=2184915#page2.tif source=2184915#page3.tif

> **PATENT** REEL: 035010 FRAME: 0755 503191174

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source=2184915#page10.tif	

PATENT REEL: 035010 FRAME: 0756

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	filed on	, or	
☐ PCT international application	n number	filed on	
The above-identified application was	made or authorized to be made	→ by me.	
I believe that I am the original invent application.	or or an original joint inventor of	a claimed invention	n in the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this de isonment of not more than five (eclaration is punish 5) years, or both.	able
In consideration of the payment by	UNITED MICROELECTRO	NICS having a	postal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hs	sin-Chu City 300), Taiwan, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ 1. d valuable consideration.	00), the receipt of	which is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements we tion and, in and to, all Letters Pa any continuations, continuation	which are disclosed atent to be obtained -in-part, divisions, r	l in the I for said renewals
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbra n this assignment;	nce has been or wi	ill be made or
I further covenant that ASSIGNEE wand documents relating to said inven known and accessible to I and will te related thereto and will promptly executed.	tion and said Letters Patent and stify as to the same in any interfo	l legal equivalents a erence, litigation or	as may be
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said cessary or desirable to carry out	Letters Patent and	said
Note: An application data sheet (PTC	D/SB/14 or equivalent), including	naming the entire	

Page 1 of 10

LEGAL NAI	ME OF INVENTOR(ASSI	GNOR)		8., 11	
Inventor:	Ching-Wen Hung		Date:	FEB 0 9 2015	
Signature:	Ching-Wen	Hung			
	Λ	1			

Page 2 of 10

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

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☐ PCT international application	number	file	ed on	***************************************
The above-identified application was	made or authorized to be	made by me.	***************************************	
I believe that I am the original invent application.	or or an original joint invent	tor of a claime	d invention in	1 the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this isonment of not more than the	nis declaratior five (5) years,	is punishab or both.	le
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No.3, Li-Hsin Road 2, Science	-Based Industrial Park	κ, Hsin-Chu	 City 300, ¹	Taiwan. R.O.C
(referred to as "ASSIGNEE" below) to acknowledged, and for other good and I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application.	d valuable consideration. ASSIGNEE and the success and to any and all improvement tion and, in and to, all Lette	sors and assiç ents which are	gnees of the a	ASSIGNEE I the
invention by the above application or substitutes, or extensions thereof, an	any continuations, continu d as to Letters Patent any i	ation-in-part, d reissue or re-d	divisions, ren examination t	ewals, thereof.
I hereby covenant that no assignment entered into which would conflict with	it, sale, agreement or encui			
I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Letters Paten stify as to the same in any i	t and legal eq interference. li	uivalents as l	may be
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and cessary or desirable to carr	said Letters F y out the prop	atent and sa	id f. (Date of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	b/SB/14 or equivalent), inclusions form. Use this form for <u>ear</u>	uding naming ch additional i	the entire nventor.	

Page 3 of 10

Docket No NAUP2420USA

Inventor: Jia-Rong Wu

Signature: Tar Pany Wu

Date: FEB 0 9 2015

Page 4 of 10

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or	,		
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☐ PCT international application	n number	filed on	
The above-identified application was	s made or authorized to be made	by me.	***************************************
I believe that I am the original invent application.	or or an original joint inventor of a	a claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	Il false statement made in this decisionment of not more than five (5	claration is punishable) years, or both.	
In consideration of the payment by	UNITED MICROELECTROICORP.	NICS having a postal add	ress of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Park, Hs	in-Chu City 300, Taiwan	, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1.0 and valuable consideration.	00), the receipt of which is her	reby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvements w tion and, in and to, all Letters Pat r any continuations, continuation-	rhich are disclosed in the tent to be obtained for said in-part, divisions, renewals	EE
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encumbrar n this assignment;	ice has been or will be made	or
I further covenant that ASSIGNEE w and documents relating to said inven known and accessible to I and will te related thereto and will promptly exe	ition and said Letters Patent and stify as to the same in any interfe	legal equivalents as may be rence, litigation proceeding	ts
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said Lecessary or desirable to carry out	etters Patent and said the proposes thereof.	f signing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including s form. Use this form for each add	naming the entire ditional inventor.	

Page 5 of 10

LEGAL NAME OF INVENTOR(ASSIGNOR) Inventor:

Chih-Sen Huang

Date: FEB 0 9 2015

Page

NPO#NAU-P2420-USA:0 CUST#UMCD-2014-0636

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here	aby declare that:			
This declaration is directed to:	by deciate that.			
☑ The attached application, or				
☐ United States application nu	mber	filed on,	or	
☐ PCT international application	n number	filed on		
The above-identified application was	s made or authorized to be made	by me.	***************************************	
I believe that I am the original invent application.	or or an original joint inventor of	a claimed invention in the		
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ 1. ad valuable consideration.	00), the receipt of which is here	eby	
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.				
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WINTNESS WHEREOF, I have hereunto set hand and seal this FEB 0 9 2015 (Date of signing)				
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for <u>each additional inventor</u>				

Page 7 of 10

NPO#NAU-P2420-USA:0 CUST#UMCD-2014-0636

LEGAL NA	WE OF INVENTOR(ASSIGNOR)		·
Inventor:	Yi-Wei Chen	Date:	FEB 0 9 2015
Signature:	Y:-Wei Chen	-	

Page 8 of 10

Title of Invention: METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

As the below named inventor, I here This declaration is directed to:	eby declare that:		
☑ The attached application, or	•		
☐ United States application number		filed on	, or
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The above-identified application was	s made or authorized to be made	by me.	
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I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrar h this assignment;	nce has been or wi	ll be made or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and estify as to the same in any interfe	legal equivalents a	s may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said lecessary or desirable to carry out	Letters Patent and	said
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NPO#NAU-P2420-USA:0 CUST#UMCD-2014-0636

Docket No NAUP2420USA

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Chia Chang Hsu	Date:	FEB 0 9 2015		
Signature:	Chia chang 1254				
	A				

Page 10 of 10

NPO#NAU-P2420-USA:0 CUST#UMCD-2014-0636

RECORDED: 02/24/2015

F#NPO-P0002E-US1201 DSC0-103U012707

PATENT REEL: 035010 FRAME: 0766